Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

-Listing of Claims:

1-2. (Canceled)

3. (Previously presented) The laminate as set forth in Claim 5, wherein:

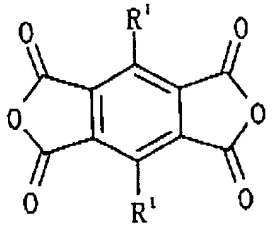
the acid dianhydride component includes the pyromellitic dianhydride in a range of from 5 mole% to 90 mole%.

4. (Previously presented) The laminate as set forth in Claim 5, wherein:

the diamine component includes the paraphenylene diamine in a range of from 25 mole% to 75 mole%, and diaminodiphenyl ether in a range of from 25 mole% to 75 mole%.

5. (Currently amended) A laminate comprising a metal layer and a polyimide film, the metal layer being directly formed on the polyimide film having a dynamic viscoelasticity whose tan δ peak is located in a range of not less than 310°C but not more than 410°C, and whose tan δ value at 300°C is not more than 0.05, the polyimide film prepared by copolymerizing an acid dianhydride component and a diamine component,

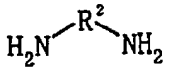
the acid dianhydride component including a pyromellitic dianhydride represented by Equation (1):



. . . (1)

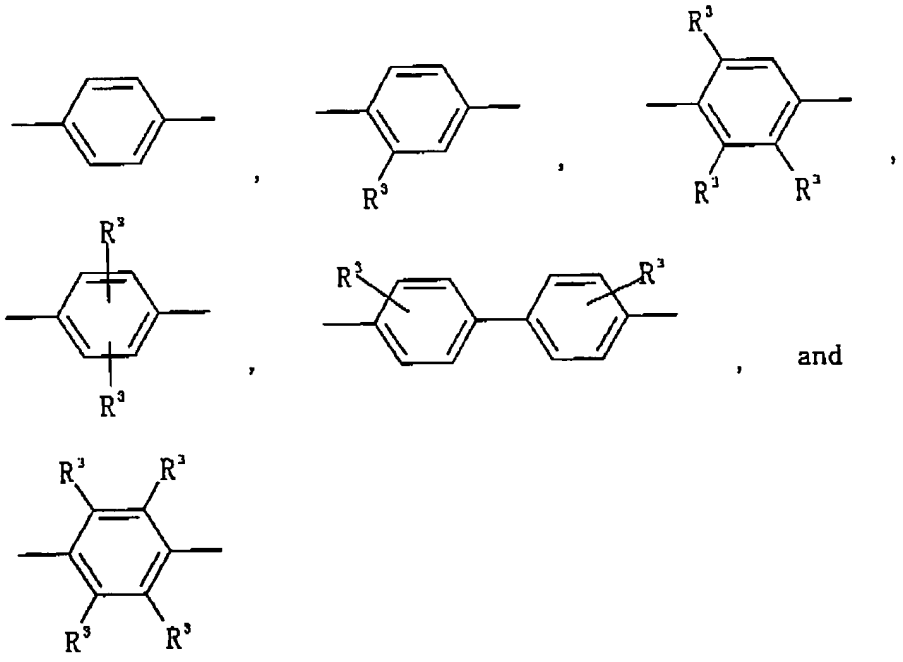
where R^1 is a residue selected from a group consisting of H-, CH_3-, CF_3, Cl-, Br-, F-, and CH_3O-, and R^1 may be the same residues or different residues, and the diamine component including a paraphenylene diamine and a diaminodiphenyl ether,

the paraphenylene diamine being represented by Equation (2):

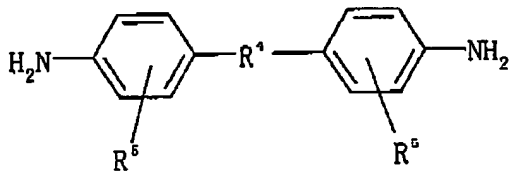


. . . (2)

where R^2 is a bivalent aromatic group selected from a group consisting of:

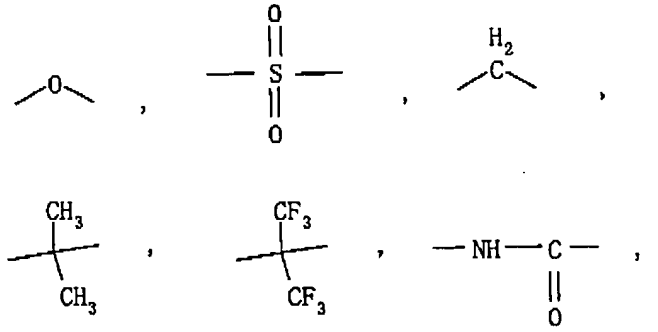


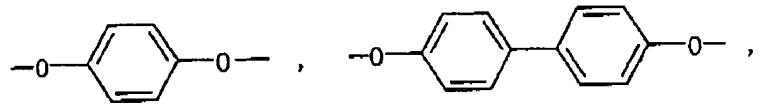
and each R^3 in the group is independently any one of -H, $-CH_3$, -OH, $-CF_3$, $-SO_4$, -COOH, $-CO-NH_2$, -Cl, -Br, -F, and $-OCH_3$, and the diaminodiphenyl ether being represented by General Formula (3):

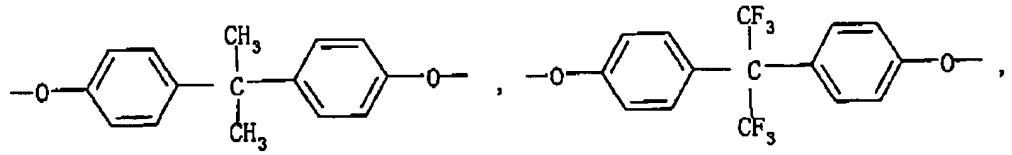


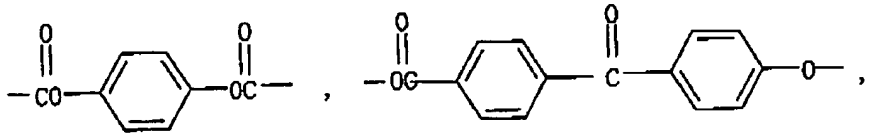
... (3)

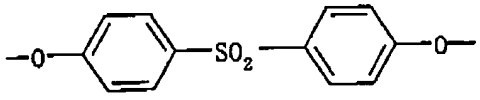
where R^4 is a bivalent organic group selected from a group consisting of:









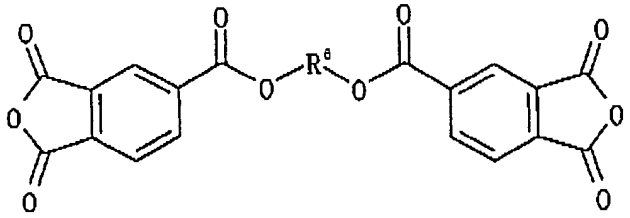
and 

and each R^5 in the group is independently any one of -H, -CH_3, -OH, -CF_3, -SO_4, -COOH, -CO-NH_2, -Cl, -Br, -F, and -OCH_3,

wherein:

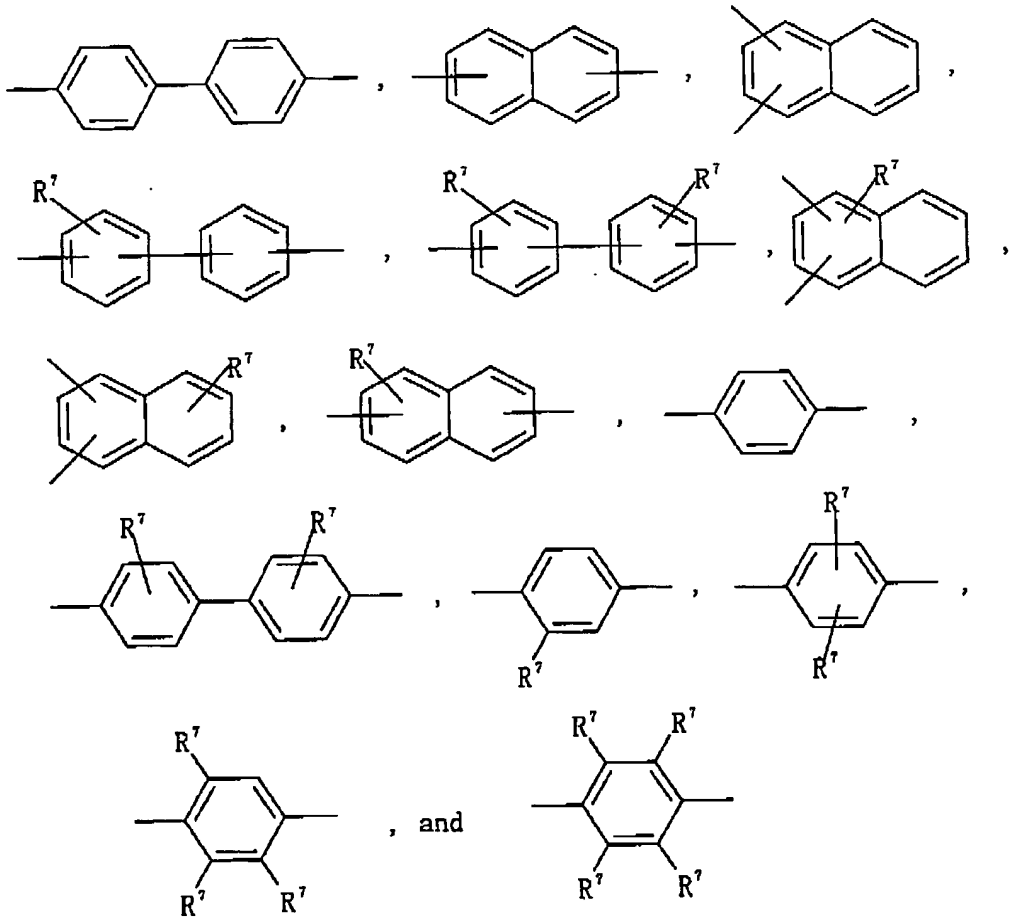
the acid dianhydride component further includes a bis(trimellitic monoester anhydride) and/or a biphenyl tetracarboxylic dianhydride,

the bis(trimellitic monoester anhydride) being represented by General Formula (4):



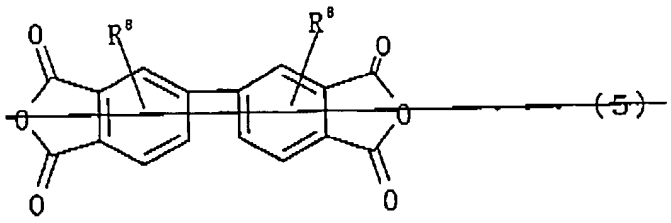
. . . (4)

where R^6 is a bivalent organic group selected from a group consisting of:



and each R^7 is independently any one of -H, -CH_3, -OH, -CF_3, -SO_4, -COOH, and -CO-NH_2; ~~and~~

~~the biphenyl tetracarboxylic dianhydride being represented by General Formula (5):~~



~~where R^s is a residue selected from a group consisting of H., CH_3-, Cl-, Br-, F- and CH_3O-, and R^s may be the same residues or the different residues.~~

6. (Previously presented) The laminate as set forth in Claim 5, wherein

the acid dianhydride component includes the bis(trimellitic monoester anhydride) in a range of from 20 mole% to 40 mole%.

7. (Previously presented) The laminate as set forth in Claim 5, wherein

the acid dianhydride component includes the biphenyl tetracarboxylic dianhydride in a range of from 0 mole% to 50 mole%.

8. (Previously presented) The laminate as set forth in Claim 5, wherein:

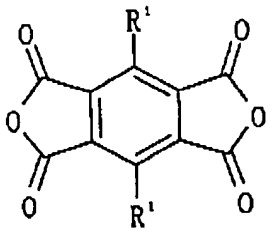
the polyimide film has a coefficient of hygroscopic expansion is 16ppm/%RH or less, and a water absorption percentage is 2.0% or less.

9-10. (Canceled)

11. (Previously presented) A polyimide film prepared by copolymerizing an acid dianhydride component and a diamine component,

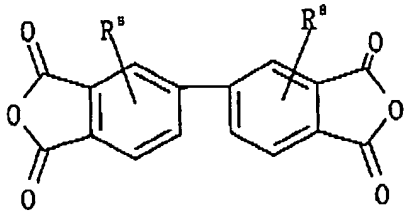
the acid dianhydride component including a pyromellitic dianhydride and a biphenyl tetracarboxylic dianhydride,

the pyromellitic dianhydride being represented by General Formula (1):



. . . (1)

where R^1 is a residue selected from a group consisting of H-, CH_3-, CF_3, Cl-, Br-, F-, and CH_3O-, and R^1 may be the same residues or different residues, and the biphenyl tetracarboxylic dianhydride being represented by General Formula (5):



. . . (5)

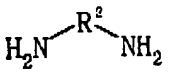
where R^8 is a residue selected from a group consisting of H-, CH_3-, Cl-, Br-, F- and CH_3O-, and R^8 may be the same residues or the different residues, and

the polyimide film having such an etching speed that one side thereof is etched with a 1N potassium hydroxide solution at an etching speed of 0.1μm/minute (one side) or higher.

12. (Previously presented) The polyimide film as set forth in Claim 11, wherein:

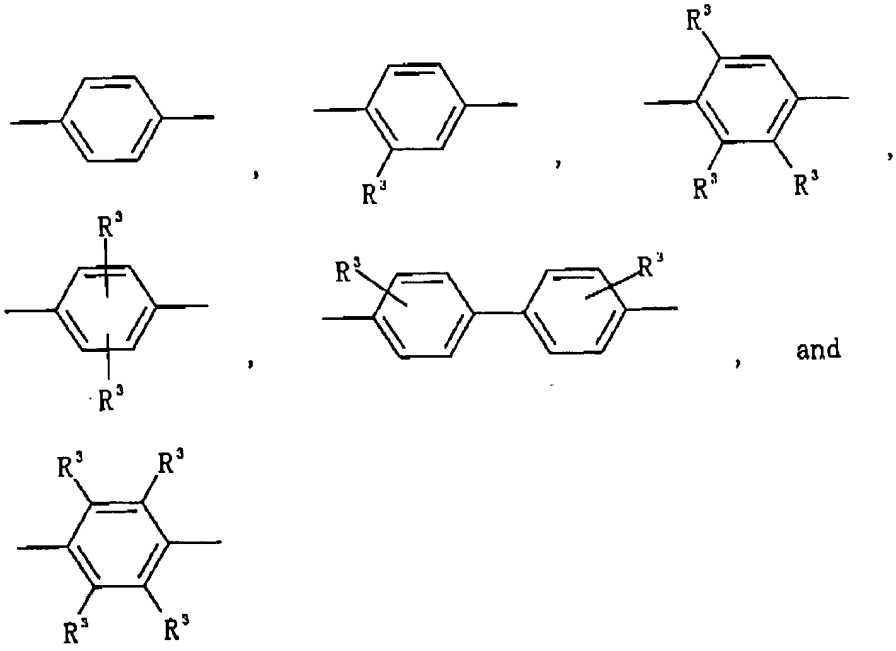
the diamine component includes a paraphenylene diamine and/or a diaminodiphenyl ether,

the paraphenylene diamine being represented by General Formula (2):

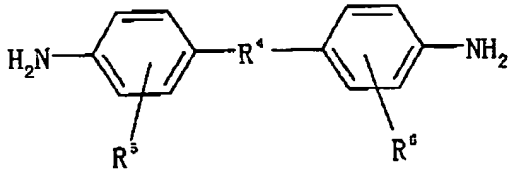


$$\cdots (2)$$

where R^2 is a bivalent aromatic group selected from a group consisting of:

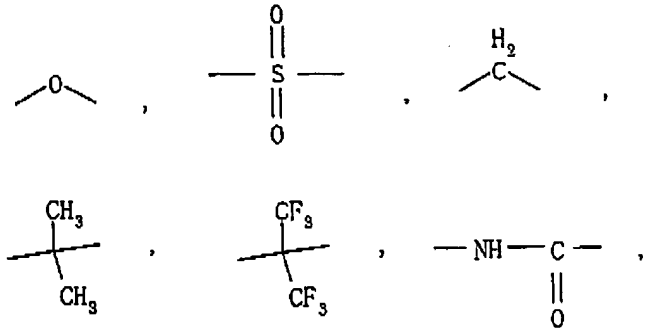


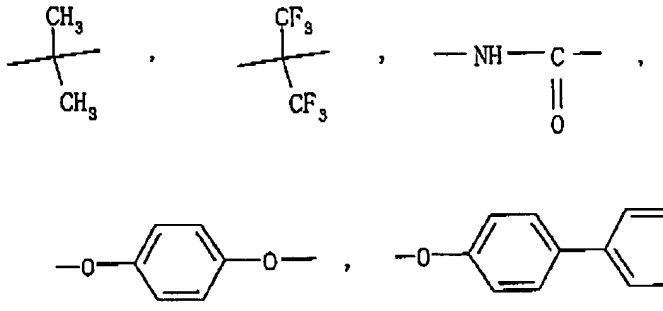
and each R^3 in the group is independently any one of -H, $-CH_3$, -OH, $-CF_3$, $-SO_4$, -COOH, $-CO-NH_2$, -Cl, -Br, -F, and $-OCH_3$, and the diaminodiphenyl ether being represented by General Formula (3):

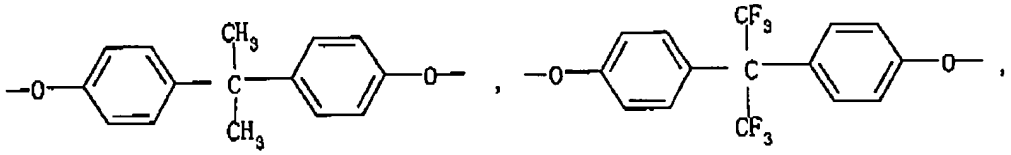


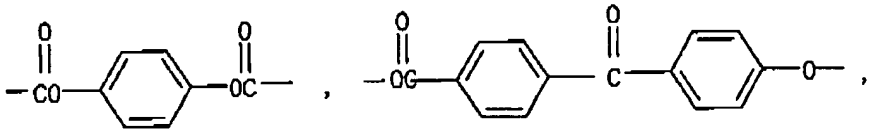
... (3)

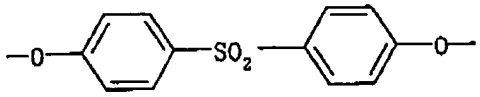
where R^4 is a bivalent organic group selected from a group consisting of:









and 

and each R^5 in the group is independently any one of -H, -CH_3, -OH, -CF_3, -SO_4, -COOH, -CO-NH_2, -Cl, -Br, -F, and -OCH_3.

13. (Original) The polyimide film as set forth in Claim 11, wherein:

the acid dianhydride component includes the pyromellitic dianhydride in a range of from 30 mole% to 99.9 mole%, and the

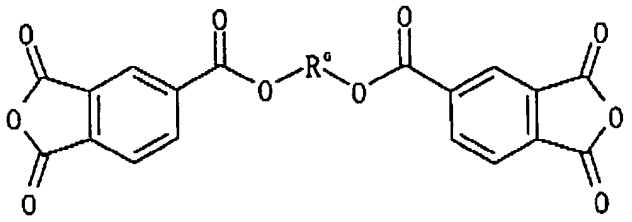
biphenyl tetracarboxylic dianhydride in a range of from 0.1 mole% to 50 mole%.

14. (Original) The polyimide film as set forth in Claim 12, wherein:

the diamine component includes the paraphenylene diamine in a range of from 15 mole% to 85 mole%, and diaminodiphenyl ether in a range of from 15 mole% to 85 mole%.

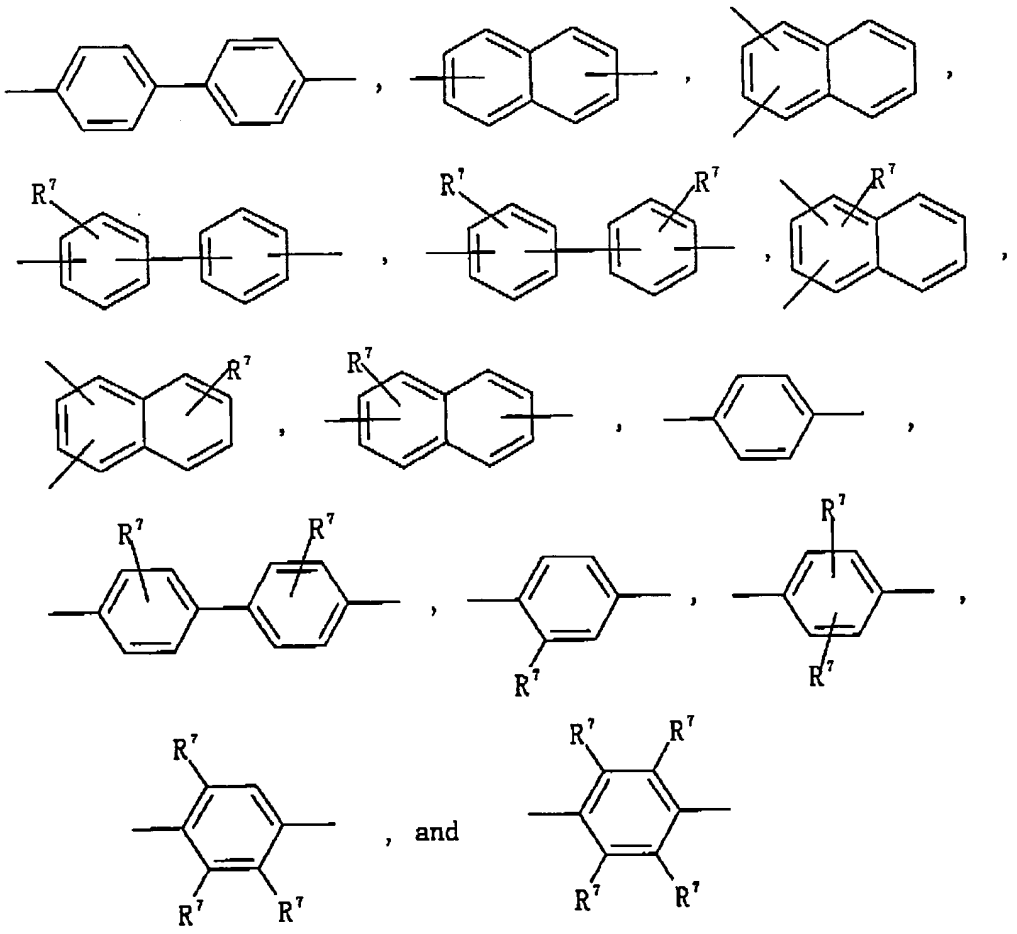
15. (Previously presented) The polyimide film as set forth in Claim 12,

the acid dianhydride component further includes a bis(trimellitic monoester anhydride) being represented by General Formula (4):



. . . (4)

where R^6 is a bivalent organic group selected from a group consisting of:



and each R^7 is independently any one of -H, -CH_3, -OH, -CF_3, -SO_4, -COOH, and -CO-NH_2.

16. (Original) The polyimide film as set forth in Claim 15, wherein:

The acid dianhydride component includes the bis(trimellitic monoester anhydride) in a range of from 10 mole% to 50 mole%.

17. (Original) The polyimide film as set forth in Claim 11, wherein:

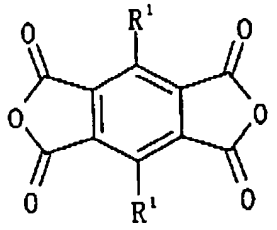
a retention percent of tear-through resistance of the polyimide film after exposing the polyimide film to environment of a temperature of 150°C, a humidity of 100%RH, and 4 atmospheric pressure for 48 hours is not less than 50%.

18. (Currently amended) ~~Laminate, comprising:~~

~~a metal layer; and~~ A laminate that is manufactured with

a polyimide film that is prepared by copolymerizing an acid dianhydride component and a diamine component,

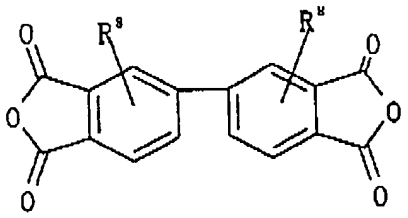
the acid dianhydride component including a pyromellitic dianhydride and a biphenyl tetracarboxylic dianhydride, the pyromellitic dianhydride being represented by General Formula (1):



· · · (1)

where R^1 is a residue selected from a group consisting of H-, CH_3-, CF_3, Cl-, Br-, F-, and CH_3O-, and R^1 may be the same residues or different residues, and

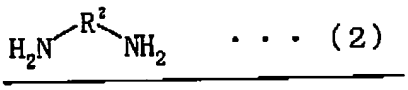
~~the~~ a biphenyl tetracarboxylic dianhydride being represented by General Formula (5):



. . . (5)

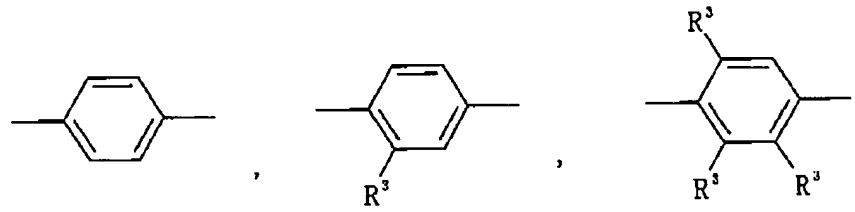
where R^8 is a residue selected from a group consisting of H-, CH_3-, Cl-, Br-, F- and CH_3O-, and R^8 may be the same residues or the different residues, ~~and~~

the diamine component including a paraphenylene diamine represented by General Formula (2)

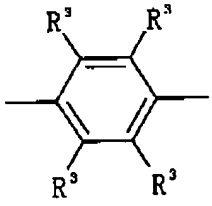


. . . (2)

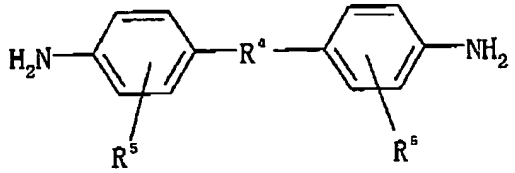
where R^2 is a bivalent aromatic group selected from a group consisting of:



and

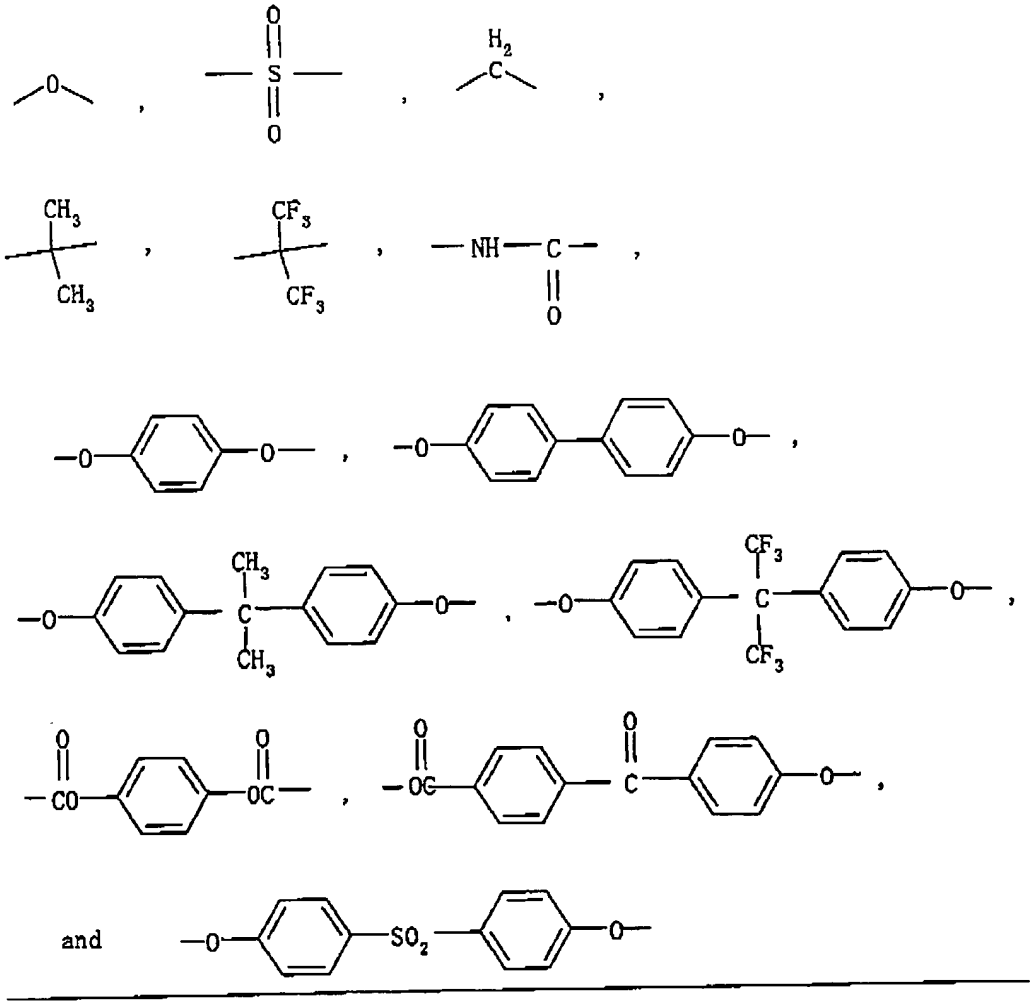


and each R^3 in the group is independently any one of -H, $-CH_3$, -OH, $-CF_3$, $-SO_4$, -COOH, $-CO-NH_2$, -Cl, -Br, -F, and $-OCH_3$, and a diaminodiphenyl ether represented by General Formula (3).



... (3)

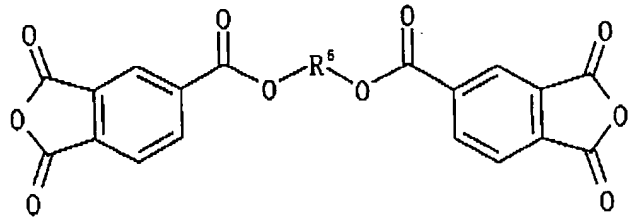
where R^4 is a bivalent organic group selected from a group consisting of:



and each R^5 in the group is independently any one of -H, $-CH_3$, -OH, $-CF_3$, $-SO_4$, -COOH, $-CO-NH_2$, -Cl, -Br, -F, and $-OCH_3$,

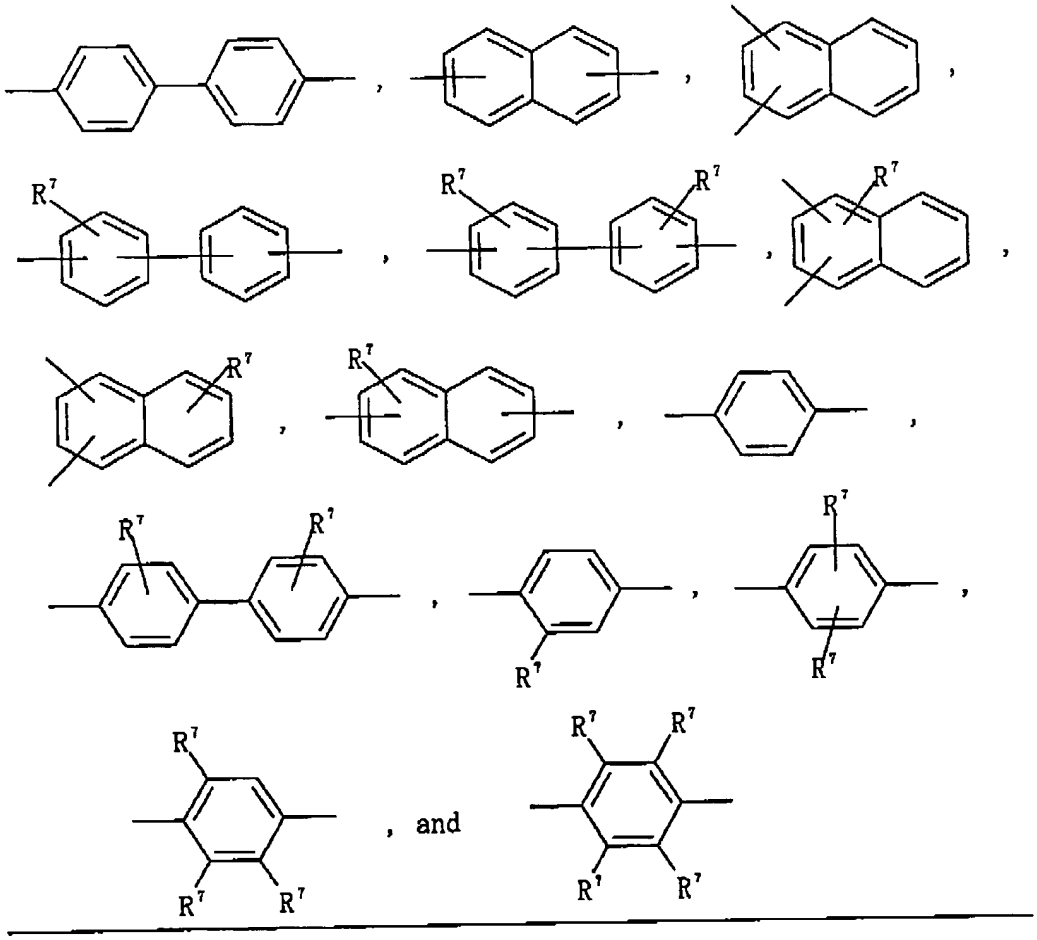
wherein:

the acid dianhydride component further including a bis(trimellitic monoester anhydride) represented by General Formula (4).



. . . (4)

where R^6 is a bivalent organic group selected from a group consisting of:



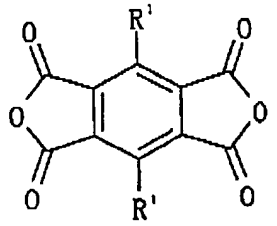
and each R^7 is independently any one of -H, -CH_3, -OH, -CF_3, -SO_4, -COOH, and -CO-NH_2,

the polyimide film having such an etching speed that one side thereof is etched with a 1N potassium hydroxide solution at an etching speed of 0.1μm/minute (one side) or higher.

19. (Previously presented) A polyimide film prepared by copolymerizing an acid dianhydride component and a diamine component,

the acid dianhydride component including the pyromellitic dianhydride, represented by General Formula (1), in a range of from 40 mole% to 80 mole%, the biphenyl tetracarboxylic dianhydride, represented by General Formula (5) in a range of from 1 mole% to 40 mole%, and the bis(trimellitic monoester anhydride, represented by General Formula (4), in a range of from 20 mole% to 50 mole%, and

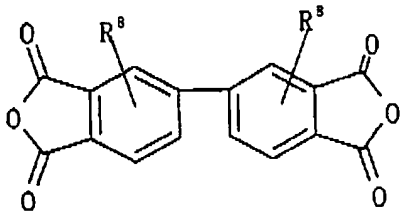
the diamine component including the paraphenylene diamine, represented by General Formula (2), in a range of 25 mole% to 75 mole%, and the diaminediphenyl ether, represented by General Formula (3), in a range of 25 mole% to 75 mole%, where General Formula (1) is:



· · · (1)

where R^1 is a residue selected from a group consisting of H-, CH_3-, CF_3, Cl-, Br-, F-, and CH_3O-, and R^1 may be the same residues or different residues;

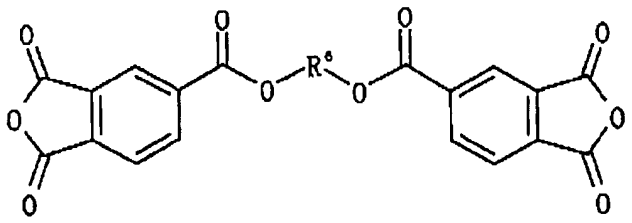
General Formula (5) is:



. . . (5)

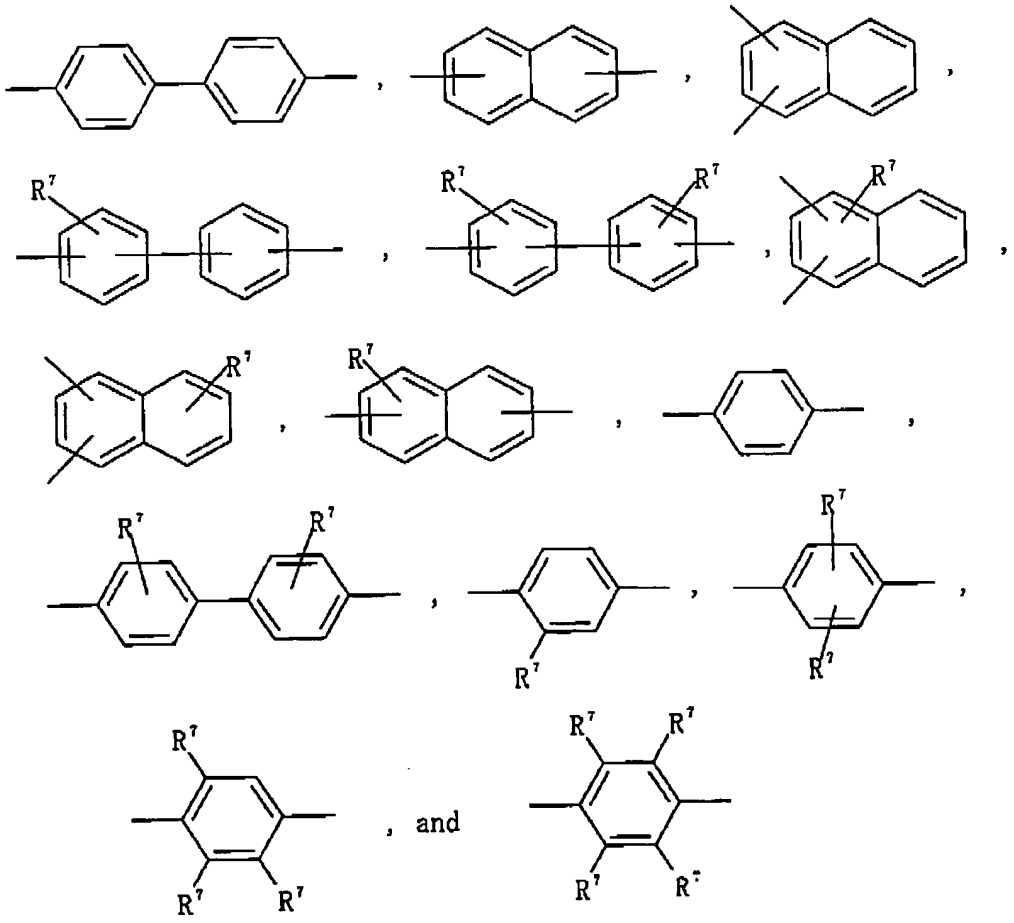
where R^8 is a residue selected from a group consisting of H-, CH_3-, Cl-, Br-, F- and CH_3O-, and R^8 may be the same residues or the different residues;

General Formula (4) is:



. . . (4)

where R^6 is a bivalent organic group selected from a group consisting of:

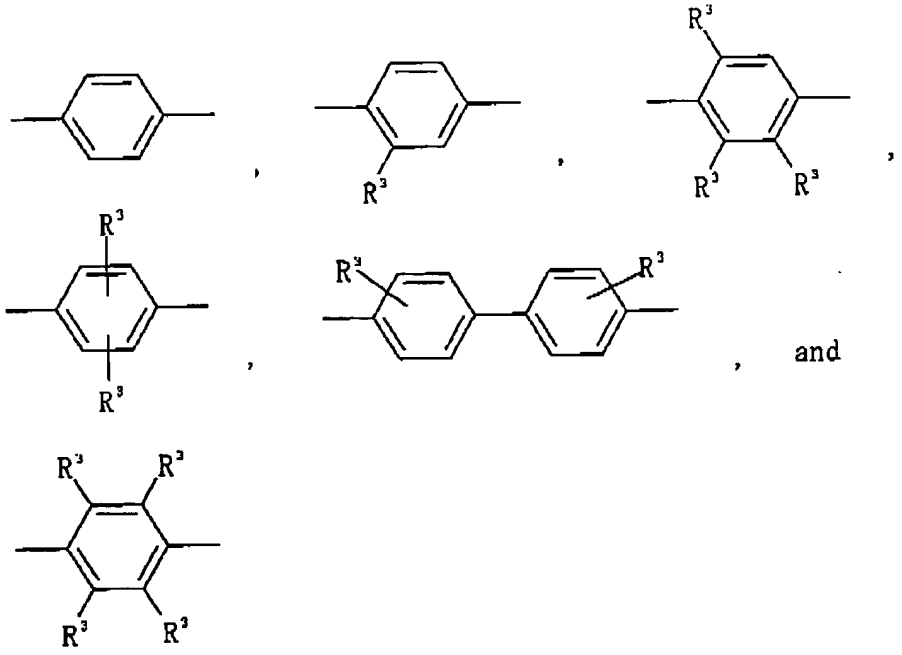


and each R^7 is independently any one of -H, $-CH_3$, -OH, $-CF_3$, $-SO_4$, -COOH, and $-CO-NH_2$;

General Formula (2) is:

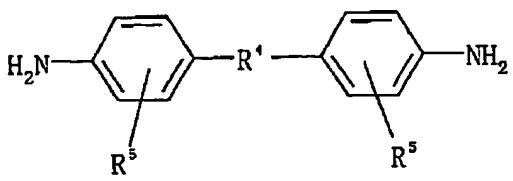
$$\cdots (2)$$

where R^2 is a bivalent aromatic group selected from a group consisting of:



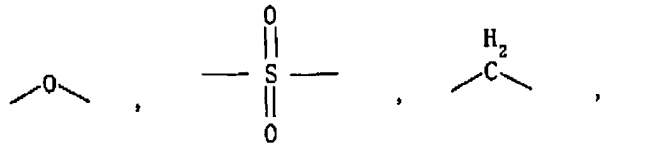
and each R^3 in the group is independently any one of -H, -CH_3, -OH, -CF_3, -SO_4, -COOH, -CO-NH_2, -Cl, -Br, -F, and -OCH_3; and

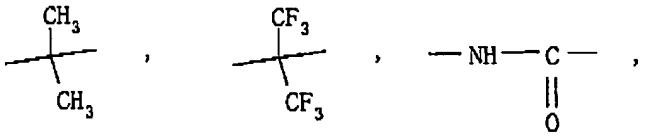
General Formula (3) is:

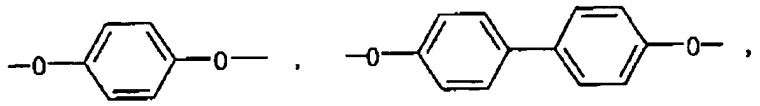


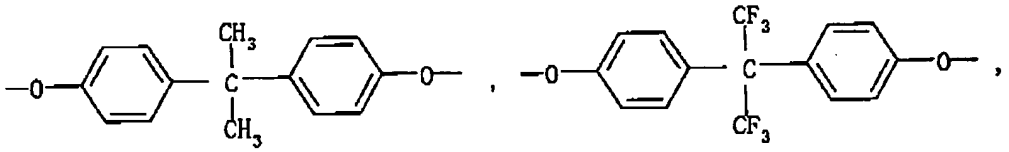
. . . (3)

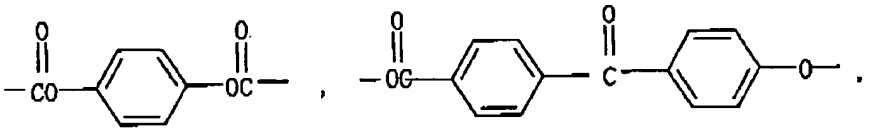
where R^4 is a bivalent organic group selected from a group consisting of:

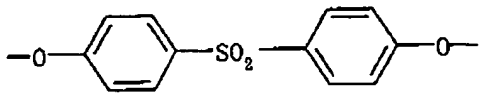










and 

and each R^5 in the group is independently any one of -H, -CH_3, -OH, -CF_3, -SO_4, -COOH, -CO-NH_2, -Cl, -Br, -F, and -OCH_3.

20. (Original) The polyimide film as set forth in Claim 19, the polyimide film having a thickness in a range of from 1μm to 200μm.

21. (Original) The polyimide film as set forth in Claim 19, the polyimide film having a modulus of elasticity in a range of from 500kg/mm^2 to 800kg/mm^2.

22. (Original) The polyimide film as set forth in Claim 19, the polyimide film having a coefficient of hygroscopic expansion in a range of from 2ppm/%RH to 20ppm/%RH.

23. (Original) The polyimide film as set forth in Claim 19, the polyimide film having a coefficient of liner expansion in a range of 1 to 30 × 10^{-6}cm/cm/°C at a temperature of from 100°C to 200°C.

24. (Original) The polyimide film as set forth in Claim 19, wherein:

a peel strength at an interface between the polyimide film and a metal layer of laminate is not less than 5N/cm, the laminate having the polyimide film and the metal layer that is formed on the polyimide film by vacuum depositing and electroplating; and

a retention rate of the peel strength is not less than 10% after exposing the laminate to environment of a temperature of 121°C and a humidity of 100%RH for 12 hours.

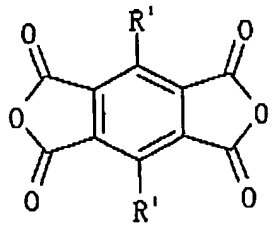
25. (Previously presented) Laminate comprising:

a metal layer; and

a polyimide film prepared by copolymerizing an acid dianhydride component and a diamine component,

the acid dianhydride component including the pyromellitic dianhydride, represented by General Formula (1), in a range of from 40 mole% to 80 mole%, the biphenyl tetracarboxylic dianhydride, represented by General Formula (5) in a range of from 1 mole% to 40 mole%, and the bis(trimellitic monoester anhydride), represented by General Formula (4), in a range of from 20 mole% to 50 mole%, and

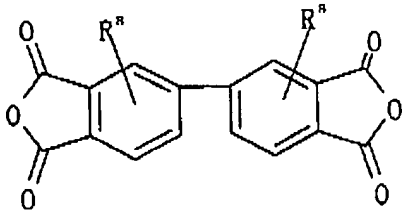
the diamine component including the paraphenylene diamine, represented by General Formula (2), in a range of 25 mole% to 75 mole%, and the diaminediphenyl ether, represented by General Formula (3), in a range of 25 mole% to 75 mole%, where General Formula (1) is:



. . . (1)

where R^1 is a residue selected from a group consisting of H-, CH_3-, CF_3, Cl-, Br-, F-, and CH_3O-, and R^1 may be the same residues or different residues;

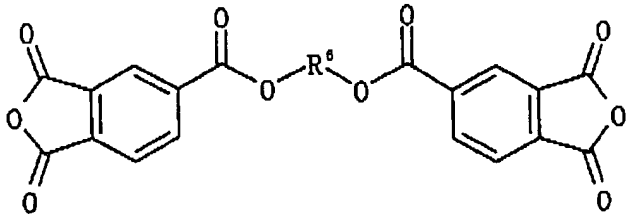
General Formula (5) is:



. . . (5)

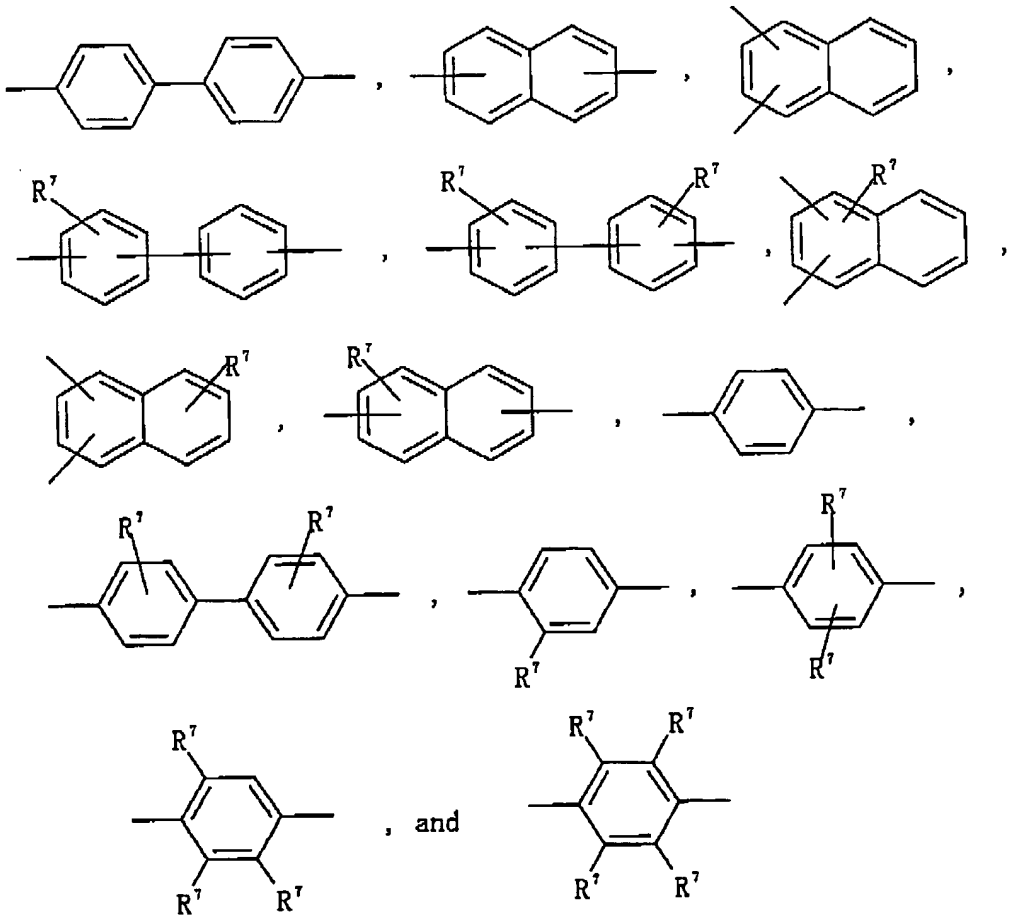
where R^8 is a residue selected from a group consisting of H-, CH_3-, Cl-, Br-, F- and CH_3O-, and R^8 may be the same residues or the different residues;

General Formula (4) is:



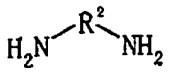
. . . (4)

where R^6 is a bivalent organic group selected from a group consisting of:



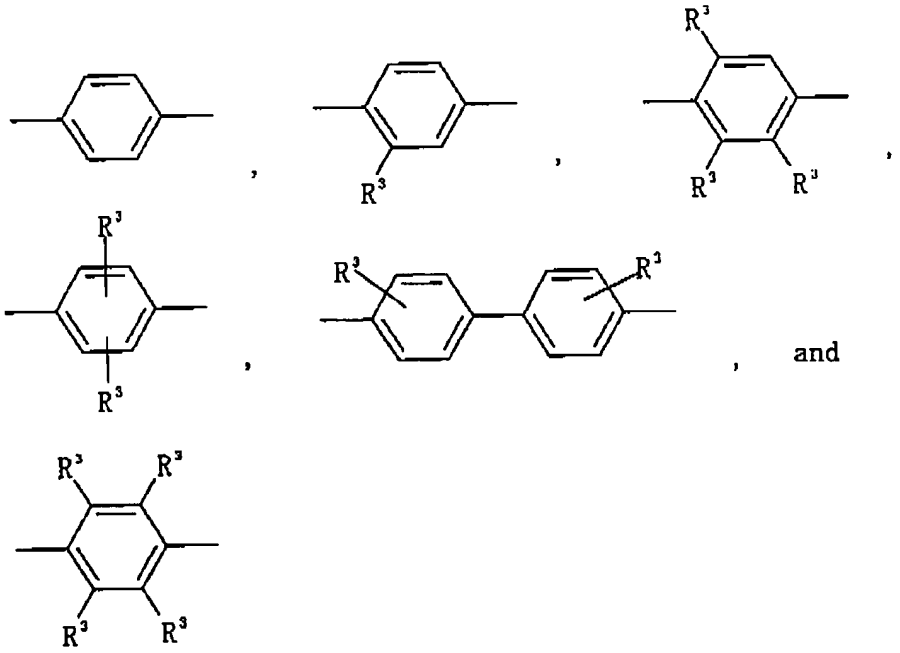
and each R^7 is independently any one of -H, $-CH_3$, -OH, $-CF_3$, $-SO_4$, -COOH, and $-CO-NH_2$;

General Formula (2) is:



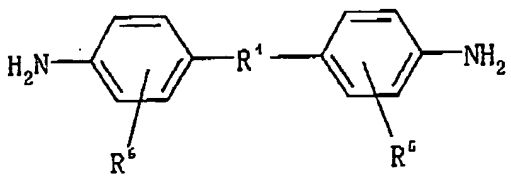
$$\cdots (2)$$

where R^2 is a bivalent aromatic group selected from a group consisting of:



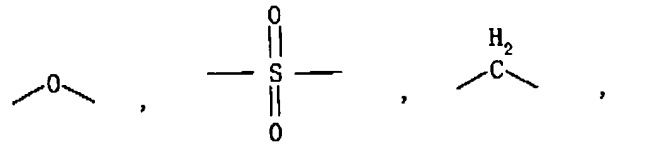
and each R^3 in the group is independently any one of -H, -CH_3, -OH, -CF_3, -SO_4, -COOH, -CO-NH_2, -Cl, -Br, -F, and -OCH_3; and

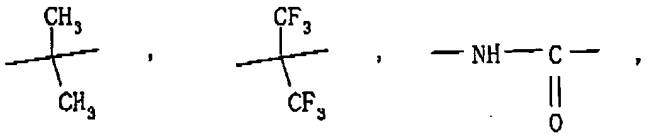
General Formula (3) is:

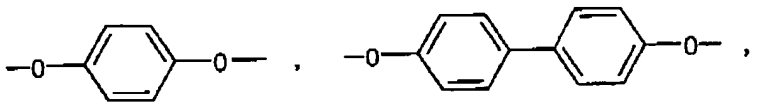


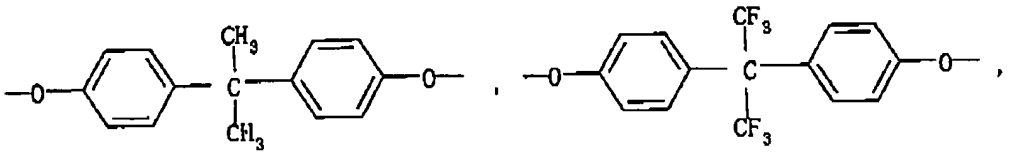
. . . (3)

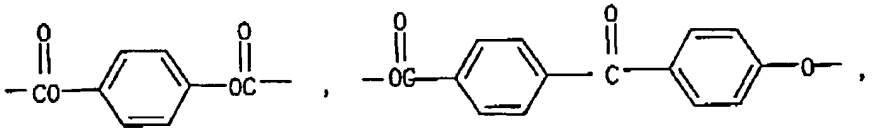
where R^4 is a bivalent organic group selected from a group consisting of:

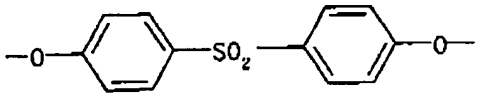






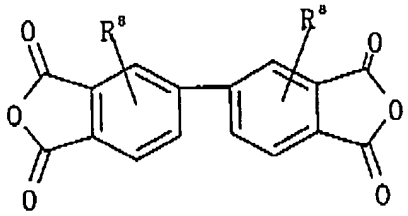




and 

and each R^5 in the group is independently any one of -H, -CH_3, -OH, -CF_3, -SO_4, -COOH, -CO-NH_2, -Cl, -Br, -F, and -OCH_3.

26. (New) The laminate as set forth in claim 5, wherein the acid dianhydride component includes a biphenyl tetracarboxylic dianhydride represented by General Formula (5)

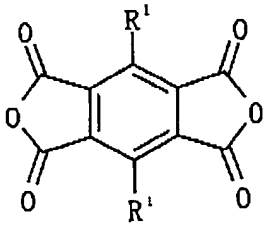


. . . (5)

where R^8 is a residue selected from a group consisting of H-, CH_3-, Cl-, Br-, F- and CH_3O-, and R^8 may be the same residues or the different residues.

27. (New) A polyimide film prepared by copolymerizing an acid dianhydride component and a diamine component,

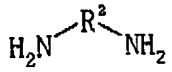
the acid dianhydride component including a pyromellitic dianhydride represented by General Formula (1),



. . . (1)

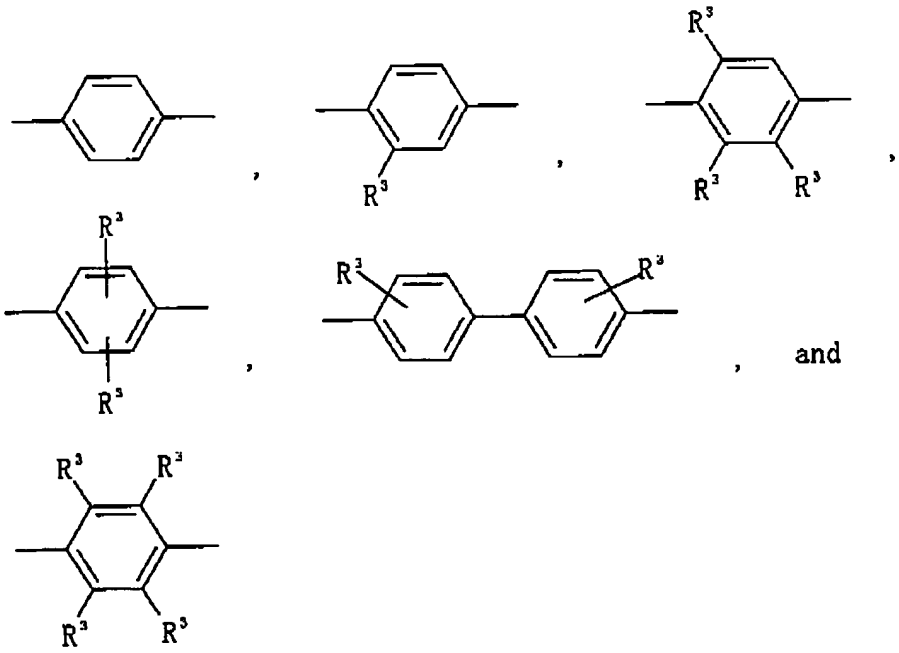
where R^1 is a residue selected from a group consisting of H-, CH_3-, CF_3, Cl-, Br-, F-, and CH_3O-, and R^1 may be the same residues or different residues, and

the diamine component including a paraphenylene diamine represented by General Formula (2)



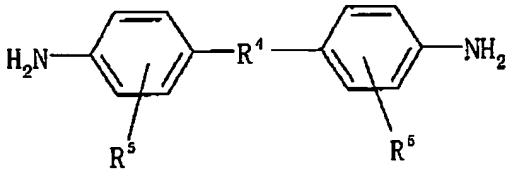
(2)

where R^2 is a bivalent aromatic group selected from a group consisting of:



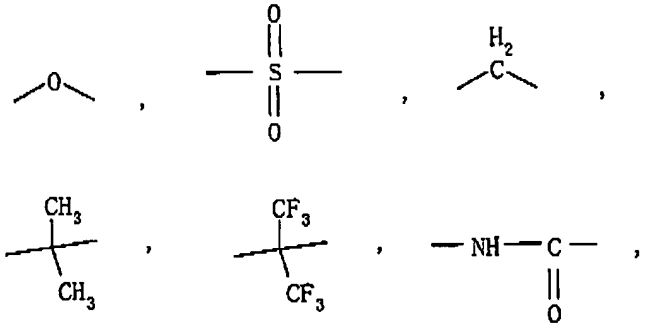
and each R^3 in the group is independently any one of -H, $-CH_3$, -OH, $-CF_3$, $-SO_4$, -COOH, $-CO-NH_2$, -Cl, -Br, -F, and $-OCH_3$, and

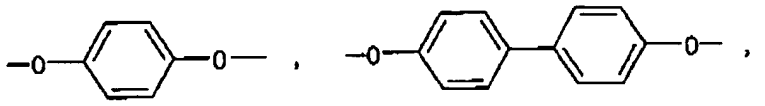
a diaminodiphenyl ether represented by General Formula (3),

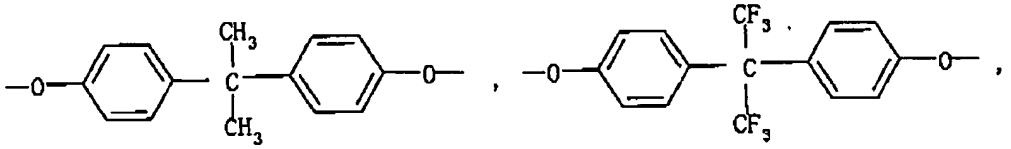


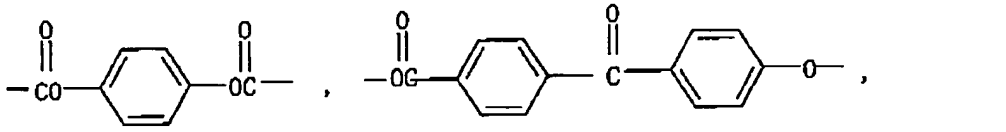
(3)

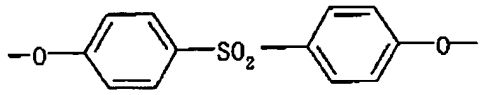
where R^4 is a bivalent organic group selected from a group consisting of:







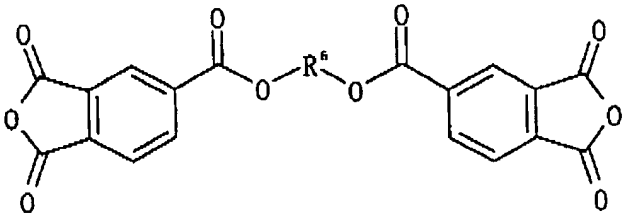


and 

and each R^5 in the group is independently any one of -H, -CH_3, -OH, -CF_3, -SO_4, -COOH, -CO-NH_2, -Cl, -Br, -F, and -OCH_3,

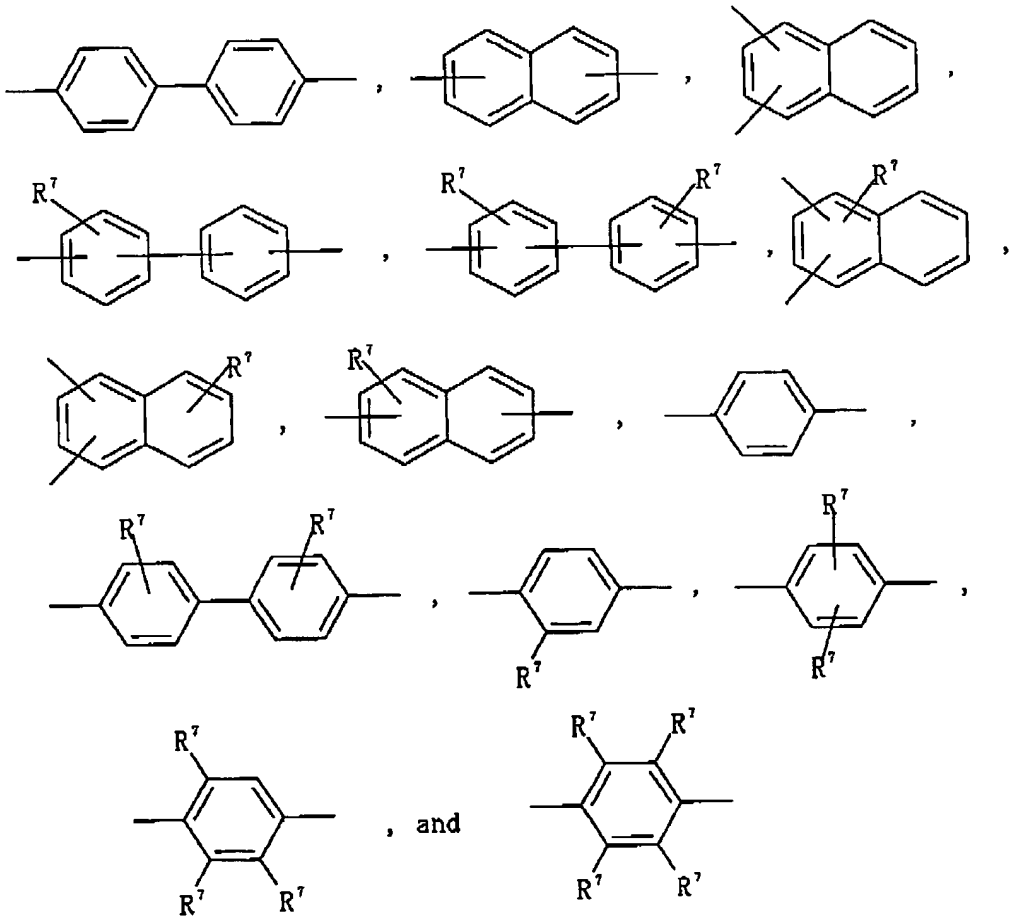
wherein:

the acid dianhydride component further including a bis(trimellitic monoester anhydride) represented by General Formula (4),



. . . (4)

where R^6 is a bivalent organic group selected from a group consisting of:

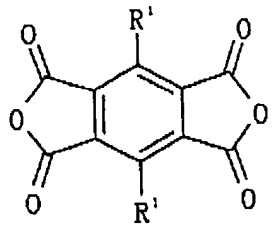


and each R^7 is independently any one of -H, $-CH_3$, -OH, $-CF_3$, $-SO_4$, -COOH, and $-CO-NH_2$,

the polyimide film having a dynamic viscoelasticity whose tan δ peak is located in a range of not less than 310°C but not more than 410°C, and whose tan δ value at 300°C is not more than 0.05.

28. (New) A polyimide film prepared by copolymerizing an acid dianhydride component and a diamine component,

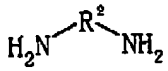
the acid dianhydride component including a pyromellitic dianhydride represented by General Formula (1),



... (1)

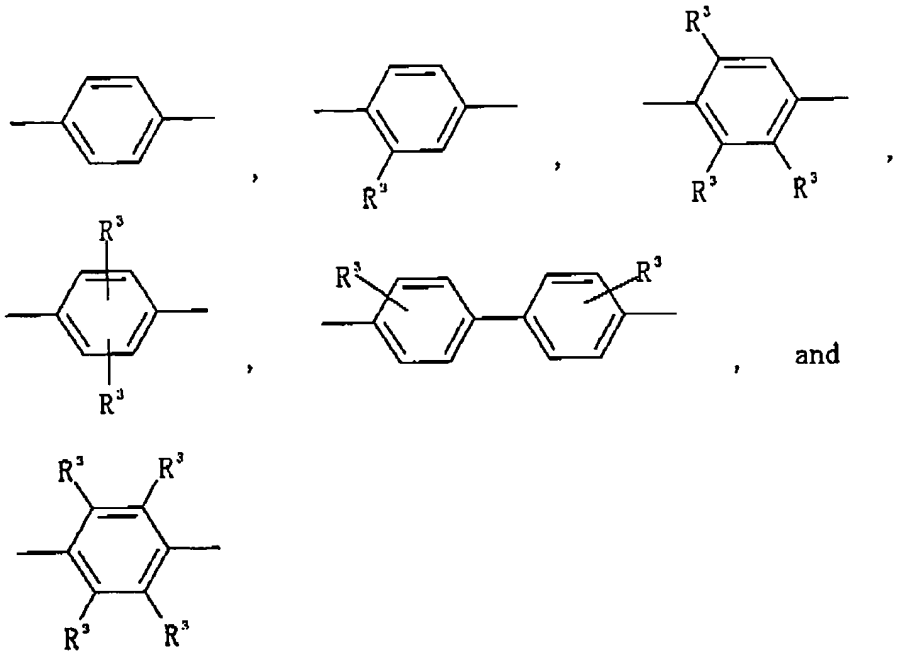
where R^1 is a residue selected from a group consisting of H-, CH_3-, CF_3, Cl-, Br-, F-, and CH_3O-, and R^1 may be the same residues or different residues, and

the diamine component including a paraphenylene diamine represented by General Formula (2)



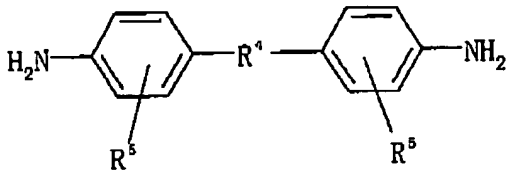
... (2)

where R^2 is a bivalent aromatic group selected from a group consisting of:



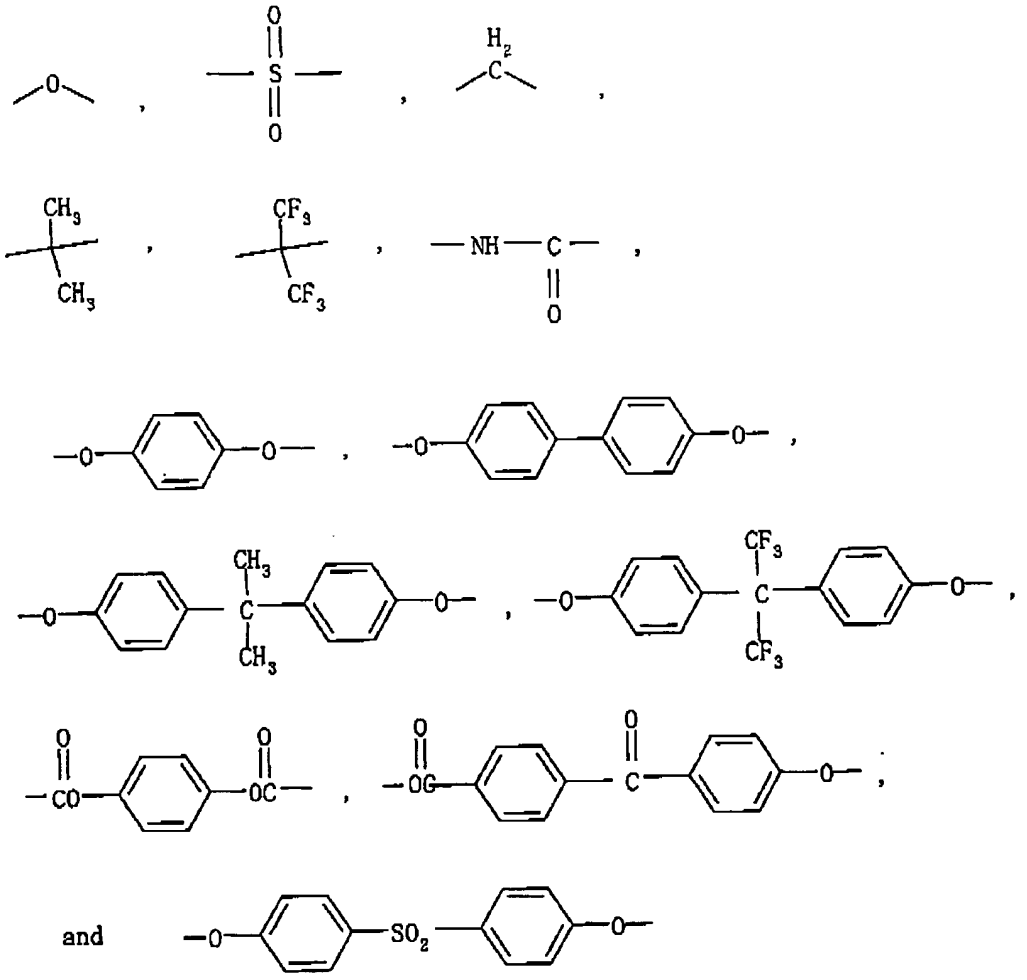
and each R^3 in the group is independently any one of -H, $-CH_3$, -OH, $-CF_3$, $-SO_4$, -COOH, $-CO-NH_2$, -Cl, -Br, -F, and $-OCH_3$, and

a diaminodiphenyl ether represented by General Formula (3),



... (3)

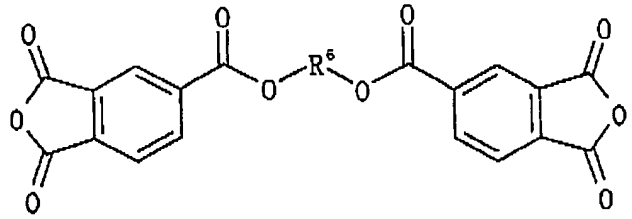
where R^4 is a bivalent organic group selected from a group consisting of:



and each R^5 in the group is independently any one of -H, -CH_3, -OH, -CF_3, -SO_4, -COOH, -CO-NH_2, -Cl, -Br, -F, and -OCH_3,

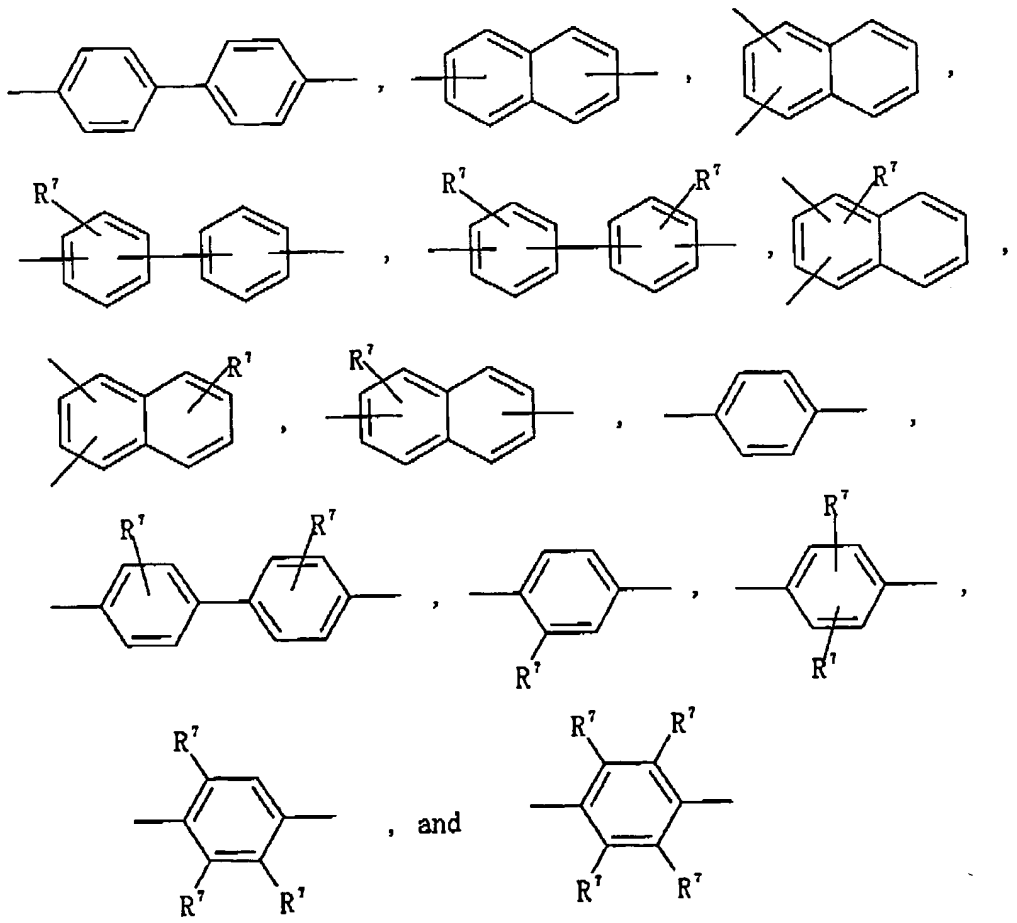
wherein:

the acid dianhydride component further including a bis(trimellitic monoester anhydride) represented by General Formula (4),



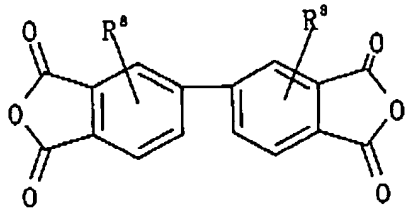
. . . (4)

where R^6 is a bivalent organic group selected from a group consisting of:



and each R^7 is independently any one of -H, $-CH_3$, -OH, $-CF_3$, $-SO_4$, -COOH, and $-CO-NH_2$, and

a biphenyl tetracarboxylic dianhydride represented by General Formula (5),

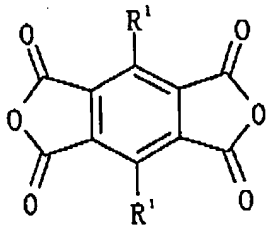


. . . (5)

where R^8 is a residue selected from a group consisting of H-, CH_3-, Cl-, Br-, F- and CH_3O-, and R^8 may be the same residues or the different residues,

the polyimide film having a dynamic viscoelasticity whose tan δ peak is located in a range of not less than 310°C but not more than 410°C, and whose tan δ value at 300°C is not more than 0.05.

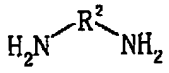
29. (New) A method in which a pyromellitic dianhydride represented by General Formula (1),



· · · (1)

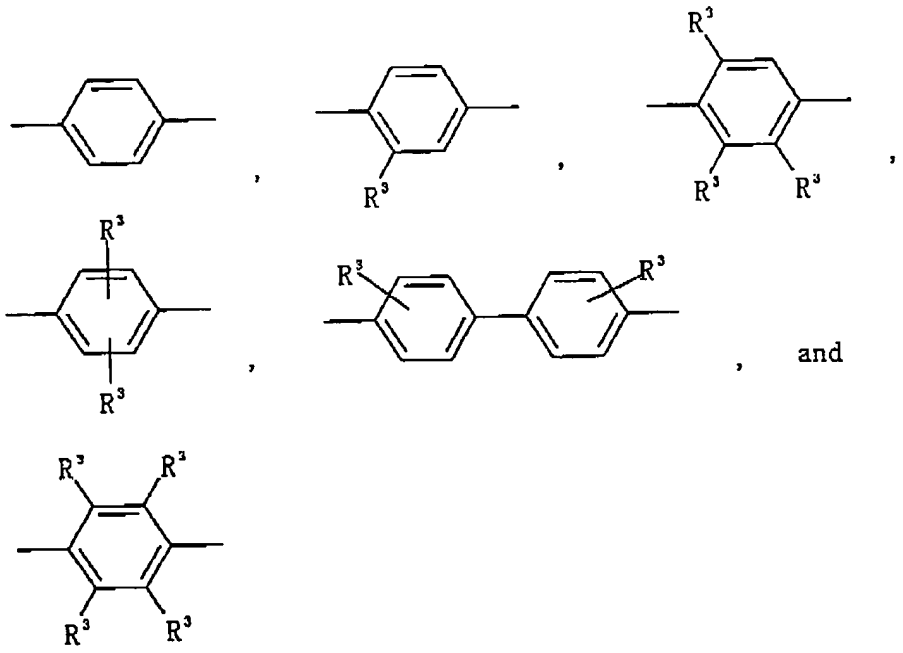
where R^1 is a residue selected from a group consisting of H-, CH_3-, CF_3, Cl-, Br-, F-, and CH_3O-, and R^1 may be the same residues or different residues,

a paraphenylene diamine represented by General Formula (2)



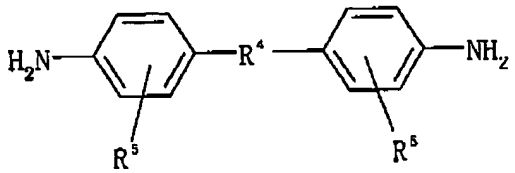
· · · (2)

where R^2 is a bivalent aromatic group selected from a group consisting of:



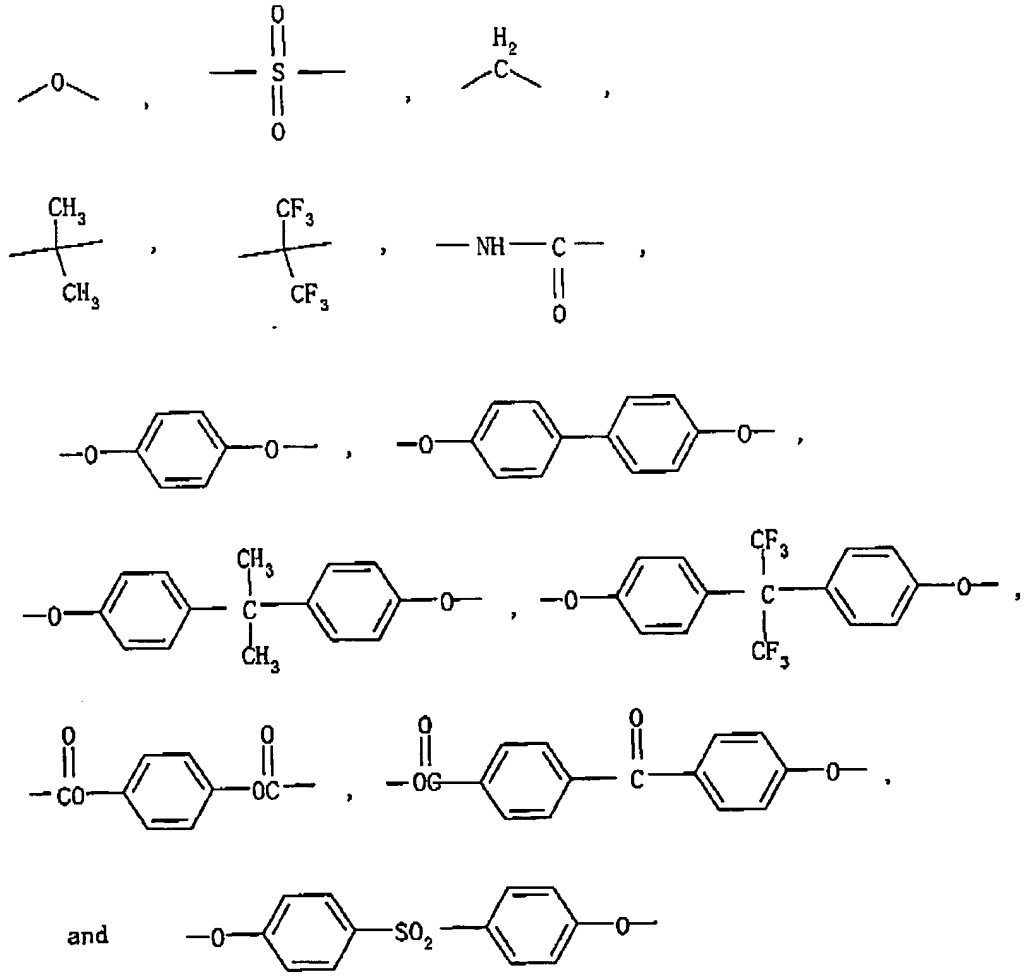
and each R^3 in the group is independently any one of -H, $-CH_3$, -OH, $-CF_3$, $-SO_4$, -COOH, $-CO-NH_2$, -Cl, -Br, -F, and $-OCH_3$, and

a diaminodiphenyl ether represented by General Formula (3),



... (3)

where R^4 is a bivalent organic group selected from a group consisting of:

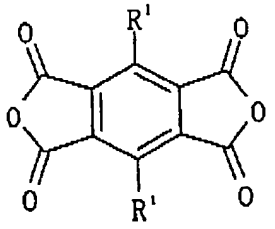


and each R^5 in the group is independently any one of -H, $-CH_3$, -OH, $-CF_3$, $-SO_4$, -COOH, $-CO-NH_2$, -Cl, -Br, -F, and $-OCH_3$,

are co-polymerized as necessary components to manufacture a polyimide film,

wherein 5 mole% to 50 mole% of p-phenylene bis(trimellitic monoester anhydride) is used as an acid dianhydride component, so that a peak of tan δ in measuring dynamic viscoelasticity of the polyimide film is controlled in a range of 310°C to 410°C.

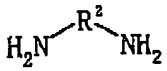
30. (New) A method for manufacturing a polyimide film, in which a pyromellitic dianhydride represented by General Formula (1),



. . . (1)

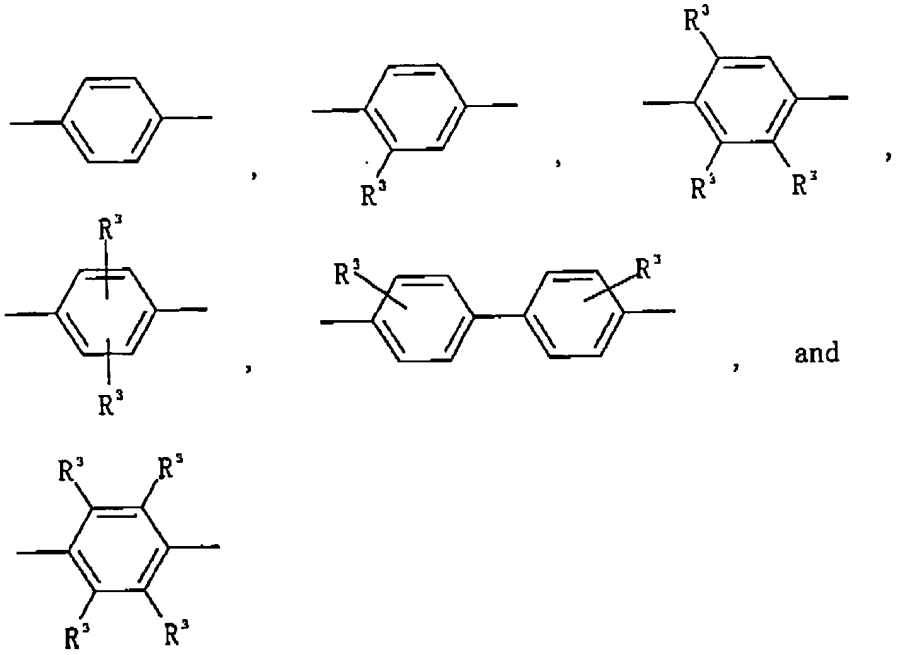
where R^1 is a residue selected from a group consisting of H-, CH_3-, CF_3, Cl-, Br-, F-, and CH_3O-, and R^1 may be the same residues or different residues,

a paraphenylene diamine represented by General Formula (2)



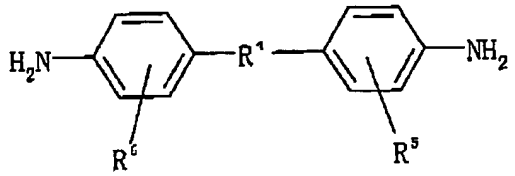
. . . (2)

where R^2 is a bivalent aromatic group selected from a group consisting of:



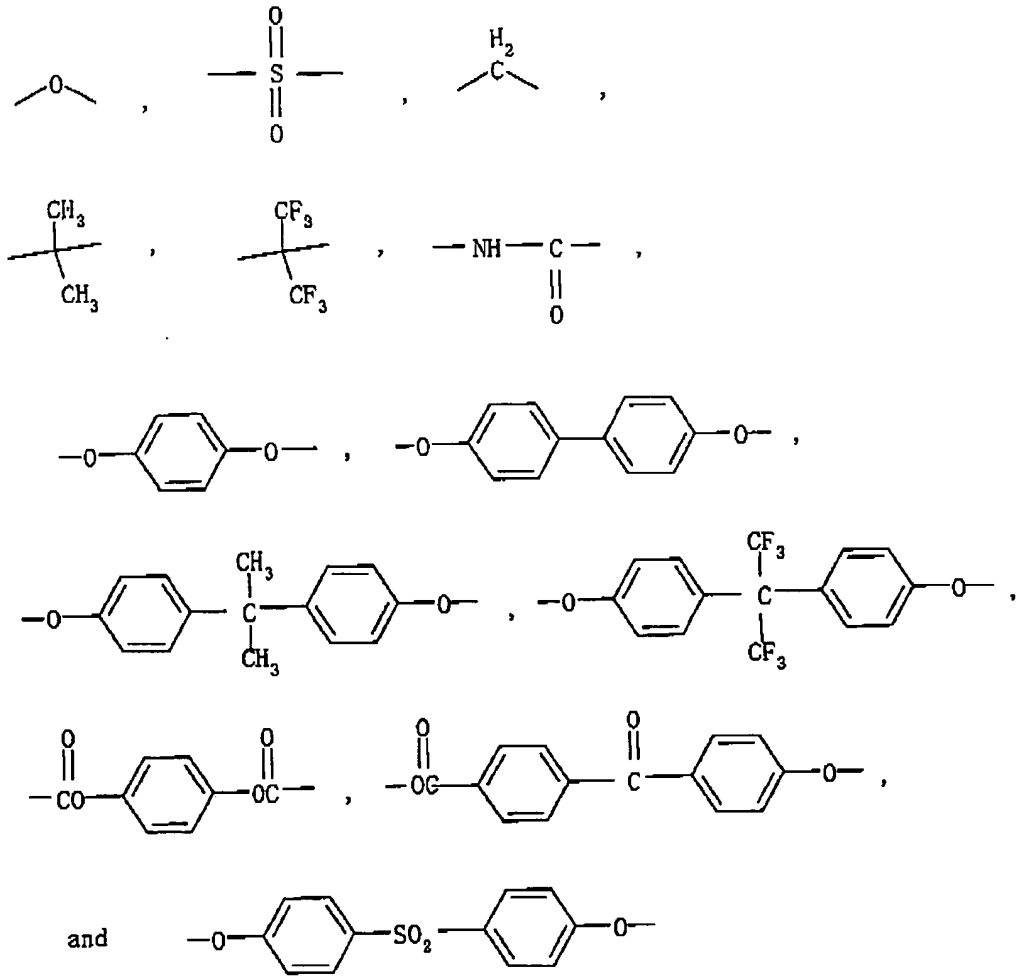
and each R^3 in the group is independently any one of -H, $-CH_3$, -OH, $-CF_3$, $-SO_4$, -COOH, $-CO-NH_2$, -Cl, -Br, -F, and $-OCH_3$, and

a diaminodiphenyl ether represented by General Formula (3),



. . . (3)

where R^4 is a bivalent organic group selected from a group consisting of:



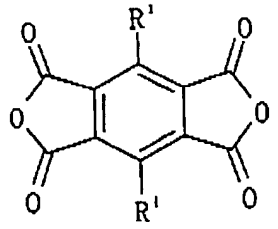
and each R^5 in the group is independently any one of -H, $-CH_3$, -OH, $-CF_3$, $-SO_4$, -COOH, $-CO-NH_2$, -Cl, -Br, -F, and $-OCH_3$,

are co-polymerized as necessary components to manufacture a polyimide film,

wherein 5 mole% to 50 mole% of p-phenylene bis(trimellitic monoester anhydride) is used as an acid dianhydride component, and

wherein a peak of tan δ in measuring dynamic viscoelasticity of the polyimide film is controlled in a range of 310°C to 410°C.

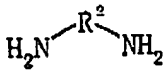
31. (New) A polyimide film in which a pyromellitic dianhydride represented by General Formula (1),



. . . (1)

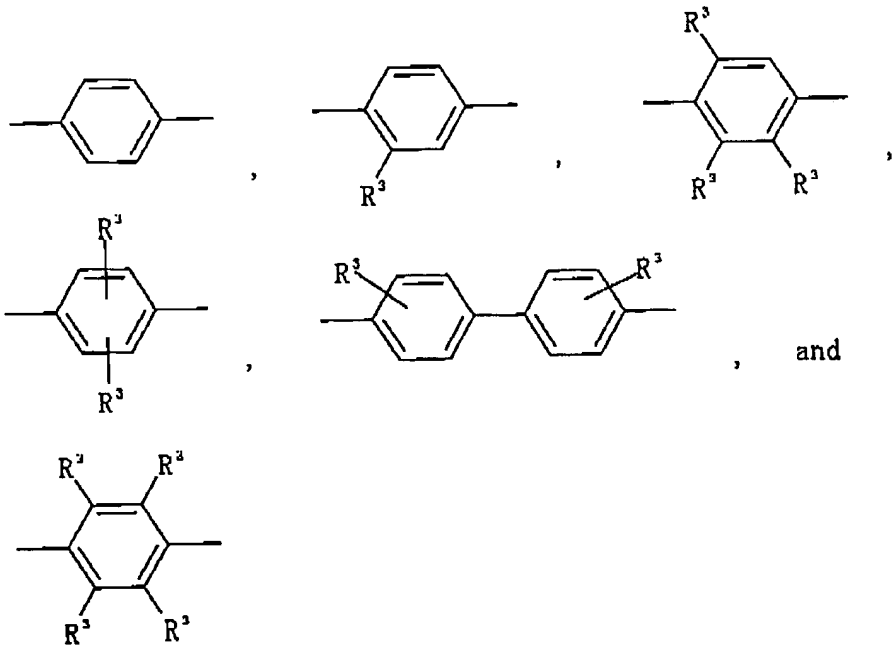
where R^1 is a residue selected from a group consisting of H-, CH_3-, CF_3, Cl-, Br-, F-, and CH_3O-, and R^1 may be the same residues or different residues,

a paraphenylene diamine represented by General Formula (2)



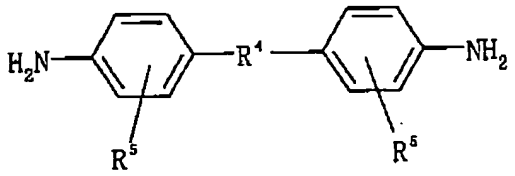
. . . (2)

where R^2 is a bivalent aromatic group selected from a group consisting of:



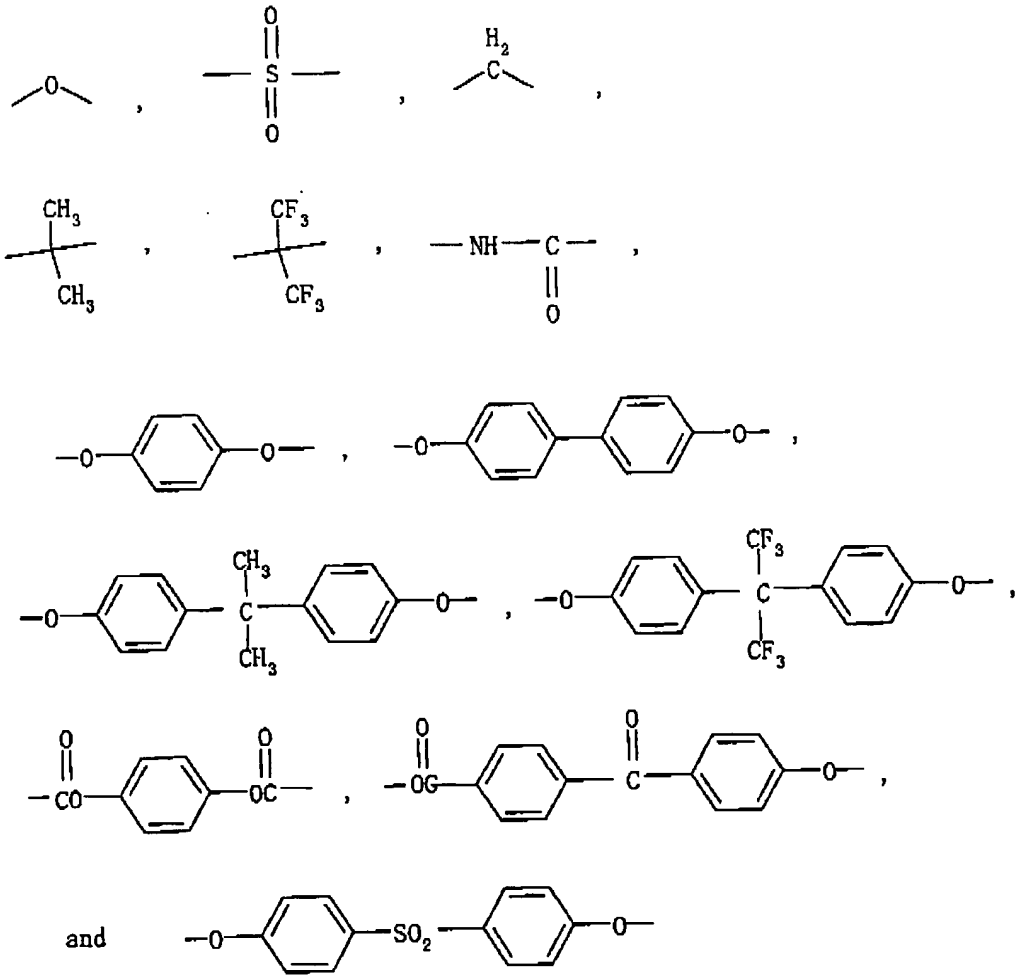
and each R^3 in the group is independently any one of -H, $-CH_3$, -OH, $-CF_3$, $-SO_4$, -COOH, $-CO-NH_2$, -Cl, -Br, -F, and $-OCH_3$,

and a diaminodiphenyl ether represented by General Formula (3),



. . . (3)

where R^4 is a bivalent organic group selected from a group consisting of:



and each R^5 in the group is independently any one of -H, -CH_3, -OH, -CF_3, -SO_4, -COOH, -CO-NH_2, -Cl, -Br, -F, and -OCH_3,

are co-polymerized as necessary components,

the polyimide film being manufactured by a method in which 5 mole% to 50 mole% of p-phenylene bis(trimellitic monoester anhydride) is used as an acid dianhydride component, and in which a peak of tan δ in measuring dynamic viscoelasticity of the polyimide film is controlled in a range of 310°C to 410°C.